

APPARATUSES AND METHODS FOR CLEANING TEST PROBES

ABSTRACT OF THE DISCLOSURE

Apparatuses and methods for cleaning test probes used in a semiconductor testing machine of the type having a plurality of test probes configured to contact the surface of a semiconductor wafer to test one or more dies formed thereon. In one embodiment, the apparatus includes a roller-support arm and a cylindrical roller supported by the roller-support arm. The roller has an outer surface comprising a sticky material. Debris on the probes will adhere to the sticky material as roller is rolled across tips of the probes. The probes are thereby cleaned.

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